

Abstract of the Disclosure

A soil-less seed support medium comprising a seed-bearing substrate superposed upon a cellular substrate contained within a rigid, porous cup-shaped modular receptacle is disclosed. Alternatively, a seed support medium comprising a seed-bearing cellular substrate contained within a rigid, porous cup-shaped modular receptacle is disclosed. Both embodiments are modular in design for ease in packaging, shipping, implanting and transplanting. A method for germinating a seed utilizing the seed support medium is also disclosed.